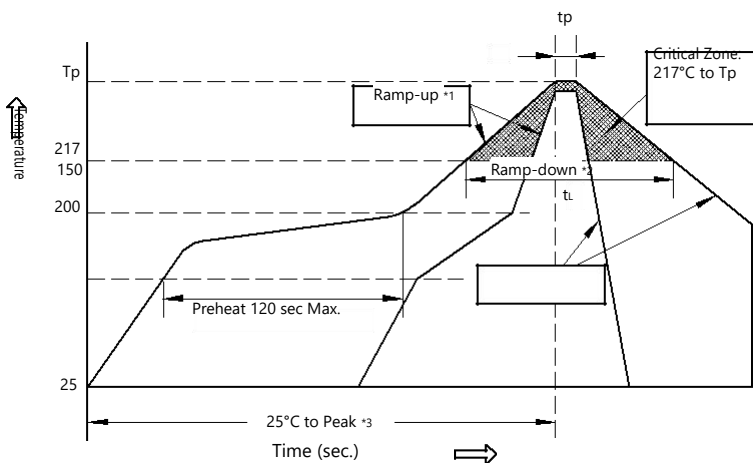


Applicable to Chip Type Aluminum Electrolytic Capacitors

Recommended Conditions for Reflow Soldering

- (1) A thermal condition system such as infrared radiation (IR) or hot blast should be adopted, and vapor heat transfer systems (VPS) are not recommended.
- (2) Reflow soldering should be within 2 cycles. Please make sure that the parts have enough cooling time.
- (3)
 - The time of preheating from 150°C to 200°C shall be within maximum 120 seconds;
 - The time of soldering temperature at 217°C measured on capacitors' top shall not exceed t_L (second);
 - The peak temperature on capacitors' top shall not exceed T_p (°C), and the time within 5°C of actual peak temperature shall not exceed t_p (second).

Classification Reflow Profile



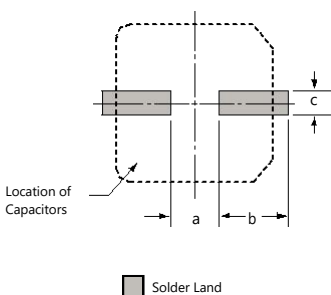
*1. Average ramp-up rate is 3.°C/second max.
*2. Ramp-down rate is 6.°C /second max.
*3. Time from 25.°C to peak temperature is 6 minutes max.

Classified at Temperature and Time

Size	Thickness (mm)	T_p (°C)	t_L (second)	t_p (second)
∅ 4, 6.3, 8, 6.2L	≥ 2.5	255	60	5
∅8× 10.5L	≥ 2.5	250	60	5
∅10×10.5L/13.5L	≥ 2.5	245	60	5
∅ 12.5, 16	≥ 2.5	240	40	5

• Please contact us if your condition is over the maximum.

Recommended Solder Land Size on PC Board (Unit: mm)



Size	a	b	c
∅4	1.0	2.6	1.6
∅5	1.4	3.0	1.6
∅6.3	1.9	3.5	1.6
∅8×6.2L	2.1	4.0	1.6
∅8×10.5L	3.0	3.5	2.5
∅10	4.0	4.0	2.5
∅12.5	4.0	6.0	3.2
∅16	6.0	7.0	3.5

